

Title (en)

A VIA CONNECTOR AND METHOD OF MAKING SAME

Title (de)

DURCHKONTAKTIERUNG UND HERSTELLUNGSMETHODE

Title (fr)

CONNECTEUR DE TRAVERSEE ET SON PROCEDE DE FABRICATION

Publication

**EP 1197131 A1 20020417 (EN)**

Application

**EP 99914213 A 19990329**

Priority

US 9906729 W 19990329

Abstract (en)

[origin: WO0059276A1] An insulator substrate or printed circuit board (PCB) having a filled and plated via is provided. The insulator substrate (12) and the sidewalls of the via are plated with conductive layer (14) and the via is filled with an electrically conductive fill composition (18). Conductive cap layers (20, 22) are formed on both ends of the conductive fill composition in the via and the major surfaces of the insulator substrate and can be bonded to a surface mount contact as a land or a pad.

IPC 1-7

**H05K 3/06**; **H05K 3/24**; **H05K 3/42**

IPC 8 full level

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CPC (source: EP)

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